ABSTRACT OF THE DISCLOSURE

A circuit board having a plurality of solder bumps is provided. The solder bumps are flattened and leveled at the tops so that the coplanarity of the solder bumps is 0.5 μm or less per 1 mm. The flattened and leveled tops of the solder bumps are formed by cold pressing, hot pressing or grinding. Method of forming such solder bumps and jigs used for carrying out such methods are also provided.